

INFORMATION DISCLOSURE CITATION IN AN APPLICATION OCT 29 2003 (if several sheets, list serial numbers of all sheets)				Document Number (Continued) TSMC-01-1388	Application Number 10/628,914		
				Applicant Chih-Ming Ke et al.			
				Filing Date 07/29/03	Drawn At U.S.		
U. S. PATENT DOCUMENTS							
EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILED DATE IF APPROPRIATE	
WV	6 1 146618	19/5/00	Komatsu	250	201.3	6/4/98	
WV	5 91671	6/6/29/99	Butsch et al.	430	30	3/13/97	
WV	6 1 30432	10/10/00	Pfeiffer et al.	250	396ML	4/13/99	
WV	5 025165	6/18/91	Chen et al.	250	491.1	3/26/90	
WV	6 0 66849	5/23/00	Masnaghetti et al.	250	310	9/8/98	
FOREIGN PATENT DOCUMENTS							
	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATED	
						YES	NO
OTHER DOCUMENTS (Including Author, Title, Date, Page(s), Etc.)							
WV	"193 nm resist shrinkage", by Su et al., Solid State Technology May 2001, pp. 52-54 and 57.						
WV	U.S. Patent Application Serial No. 10/047,366, Filed 1/14/03						
WV	"Reducing Photoresist Shrinkage via Plasma Treatment assigned to the same assignee."						
EXAMINER	ZIA R-HASHTHI	DATE CONSIDERED		12/28/04			